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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original document or copy thereof.

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1. Submission Type

☒ New☐ Resubmission (Non-Recordation)

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☐ Correction of PTO Error

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2. Name of Conveying Party(ies):

HYNIX SEMICONDUCTOR JAPAN INC.

Additional Name(s) of conveying party(s) attached? ☐ Yes ☒ No

3. Name and Address of Receiving Party(ies):

Name: HYUNDAI PLASMA CO., LTD.Street Address: 973, D, R & D, KSP Bldg., 2-1Sakado 3-chome, Takatsu-ku, KanagawaCity: Kawasaki-shiState/Country: Japan Zip: _____Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other: _____Execution Date(s): 12262001

5. Application number(s) or patent number(s):

If this document is being filed together with a new application,

☐ the first execution date of the application is: _____☒ The filing date of the application is: 07241997

A. Patent Application No.(s)

08899760

B. Patent No.(s)

6069450

6 Name and address of party to whom correspondence concerning this matter should be mailed:

CUSTOMER NUMBER 00136

or

JACOBSON HOLMAN PLLC

400 Seventh Street, N.W.

Washington, DC 20004

Tel. 202-638-6666

Attorney Docket No. P61321US0

7. Number of applications and patents

18. Total fee (37 CFR 3.41) \$ 40.00☒ Enclosed☒ Any deficiencies in enclosed fees are authorized to be charged to deposit account 06-1358

10. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Yoon S. Ham / 45,307

Name of Person Signing/ Reg. #

Signature

January 4, 2002

Date

Total number of pages excluding cover sheet:

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A S S I G N M E N T

WHEREAS, HYNIX SEMINCONDUCTOR JAPAN INC. (hereinafter Assignor, a Japanese corporation owns U.S. Letters Patent 6,069,450; and

WHEREAS, HYUNDAI PLASMA CO., LTD. (hereinafter Assignee), a Japanese corporation, located and doing business at 973, D, R & D, KSP Bldg., 2-1, Sakado 3-chome, Takatsu-ku, Kawasaki-shi, Kanagawa, Japan is desirous of acquiring the complete title and interest in said Letters Patent;

NOW, THEREFORE, in consideration of the sum of one dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor by these presents does sell, assign and transfer unto said Assignee, its successors, legal representatives, heirs and assigns the entire right, title and interest in the United States to said invention as described in Letter Patent 6,069,450, and all re-issues, or extensions of said Letters Patent to be held and enjoyed by said Assignee for its own use, or for its legal representatives, successors, heirs, and assigns to the full end of the term for which said Letters Patent is granted, and any extensions thereof, as fully and entirely as the same would have been held by said Assignor had this assignment and sale not been made, and for the same consideration said Assignor hereby covenants and agrees that at the time of execution and delivery of this instrument it is the lawful owner of the complete right, title and interest in and to said invention and

said Letters Patent above mentioned, and its interest is unencumbered and that it has good and full right and lawful authority to sell and convey its interest in the manner set forth herein; and for the same consideration Assignor hereby covenants and agrees that it will, when ever counsel for said Assignee, or counsel for its legal successors, legal representatives, heirs or assigns shall advise that any proceedings in connection with said Letters Patent or any re-issue or extension of said Letters Patent to be obtained thereon, is lawful and desirable, sign all papers and documents, make all lawful oaths, and do all acts necessary as required to be done for the procurement, maintenance, enforcement and defense of said Letters Patent, without charge to said Assignor, its successors, legal representatives, heirs and assigns, but at the expense of said Assignee, its successors, legal representatives, heirs and assigns.

Assignor hereby further assigns to Assignee all claims and causes of action for infringement of the patent rights assigned herein, including the right to sue for, and collect damages for, any and all acts of past and future infringement.

Assignor hereby grant(s) the law firm of Jacobson Holman, PLLC, 400 Seventh Street, N.W., Washington, D.C. 20004, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this

document.

Signed this 26th day of December, 2001

HYNIX SEMICONDUCTOR JAPAN INC.

Lee Yong Doo

Name : Lee Yong Doo

Title : President

Witnesses:

(1) Shinji

(2) [Signature]